

RJK5014DPP

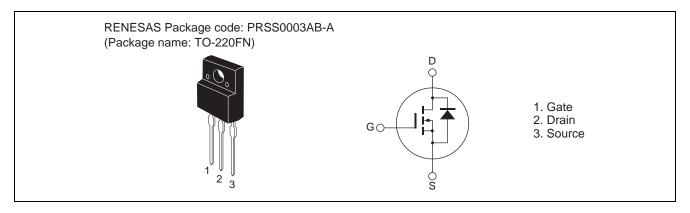
Silicon N Channel MOS FET High Speed Power Switching

REJ03G1530-0200 Rev.2.00 Dec 02, 2009

Features

- Low on-resistance $R_{DS(on)} = 0.325~\Omega~typ.~(at~I_D=9.5~A,~V_{GS}=10~V,~Ta=25~^{\circ}C)$
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	500	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D Note4	19	Α
Drain peak current	I _{D (pulse)} Note1	38	Α
Body-drain diode reverse drain current	I _{DR}	19	Α
Body-drain diode reverse drain peak current	I _{DR (pulse)} Note1	38	Α
Avalanche current	I _{AP} Note3	4	Α
Avalanche energy	E _{AR} Note3	0.88	mJ
Channel dissipation	Pch Note2	35	W
Channel to case thermal impedance	θch-c	3.57	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. Value at Tc = 25°C
- 3. STch = 25° C, Tch $\leq 150^{\circ}$ C
- 4. Limited by maximum safe operation area

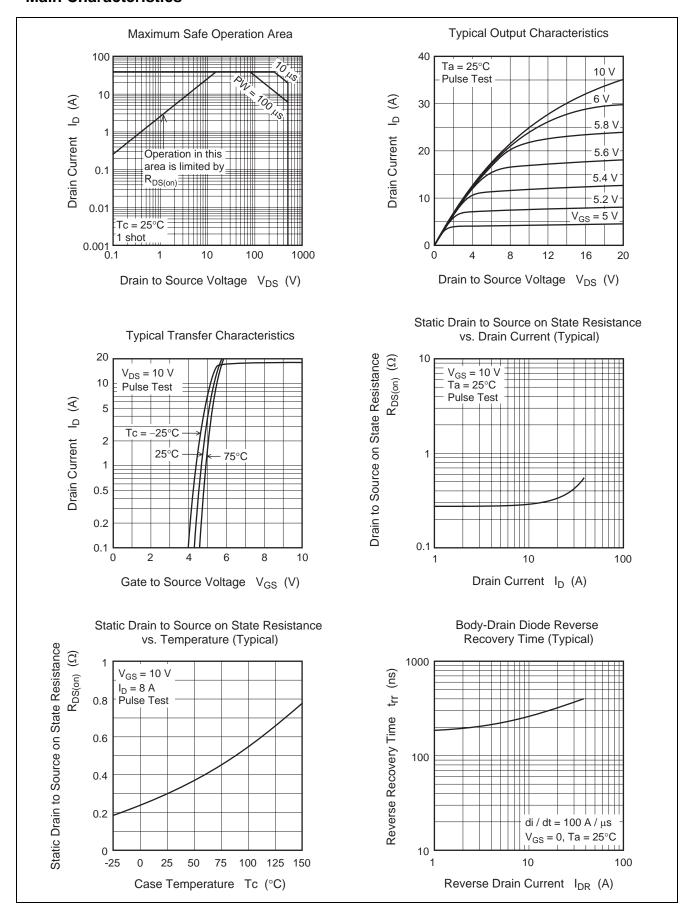
Electrical Characteristics

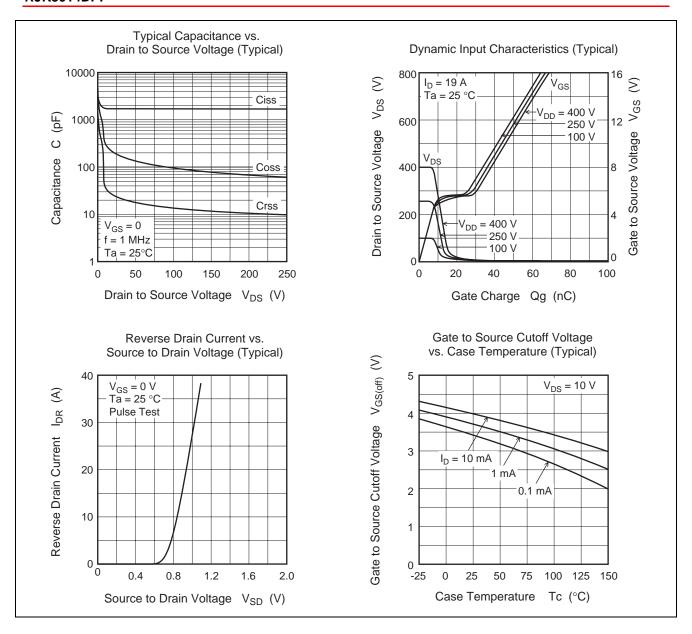
 $(Ta = 25^{\circ}C)$

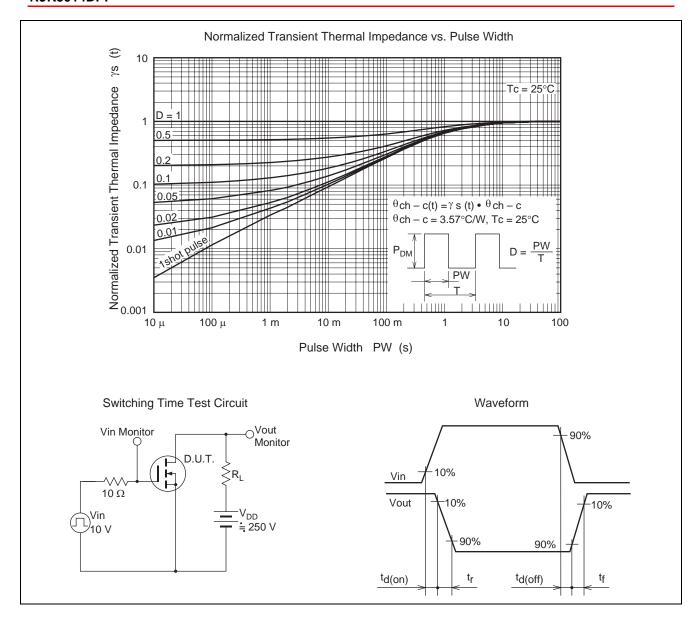
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS(on)}	_	0.325	0.390	Ω	$I_D = 9.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note5}}$
Input capacitance	Ciss	_	1800	_	pF	V _{DS} = 25 V
Output capacitance	Coss	_	190	_	pF	V _{GS} = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	24	_	pF	
Turn-on delay time	t _{d(on)}	_	36	_	ns	$I_D = 9.5 \text{ A}$
Rise time	t _r	_	41	_	ns	$V_{GS} = 10 \text{ V}$ $R_L = 26.3 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	$t_{d(off)}$	_	93	_	ns	
Fall time	t _f	_	39	_	ns	
Total gate charge	Qg	_	46	_	nC	V _{DD} = 400 V
Gate to source charge	Qgs	_	9	_	nC	V _{GS} = 10 V I _D = 19 A
Gate to drain charge	Qgd	_	20	_	nC	
Body-drain diode forward voltage	V_{DF}	_	0.91	1.55	V	I _F = 19 A, V _{GS} = 0 Note5
Body-drain diode reverse recovery time	t _{rr}	_	320	_	ns	$I_F = 19 \text{ A}, V_{GS} = 0$ di _F /dt = 100 A/ μ s

Notes: 5. Pulse test

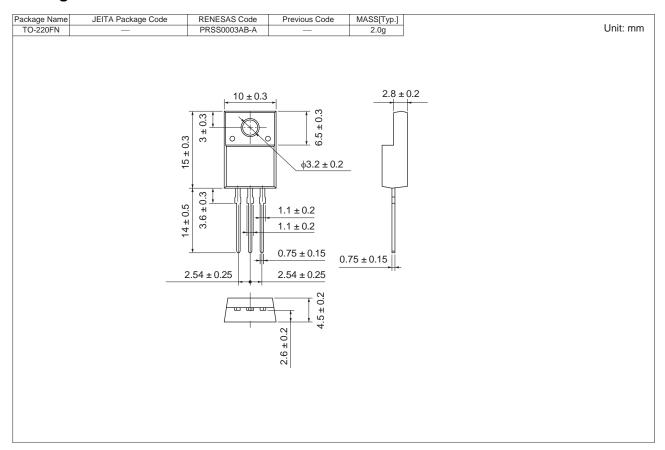
Main Characteristics







Package Dimensions



Ordering Information

Part No.	Quantity	Shipping Container
RJK5014DPP-00-T2	1050 pcs	Box (Tube)

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